

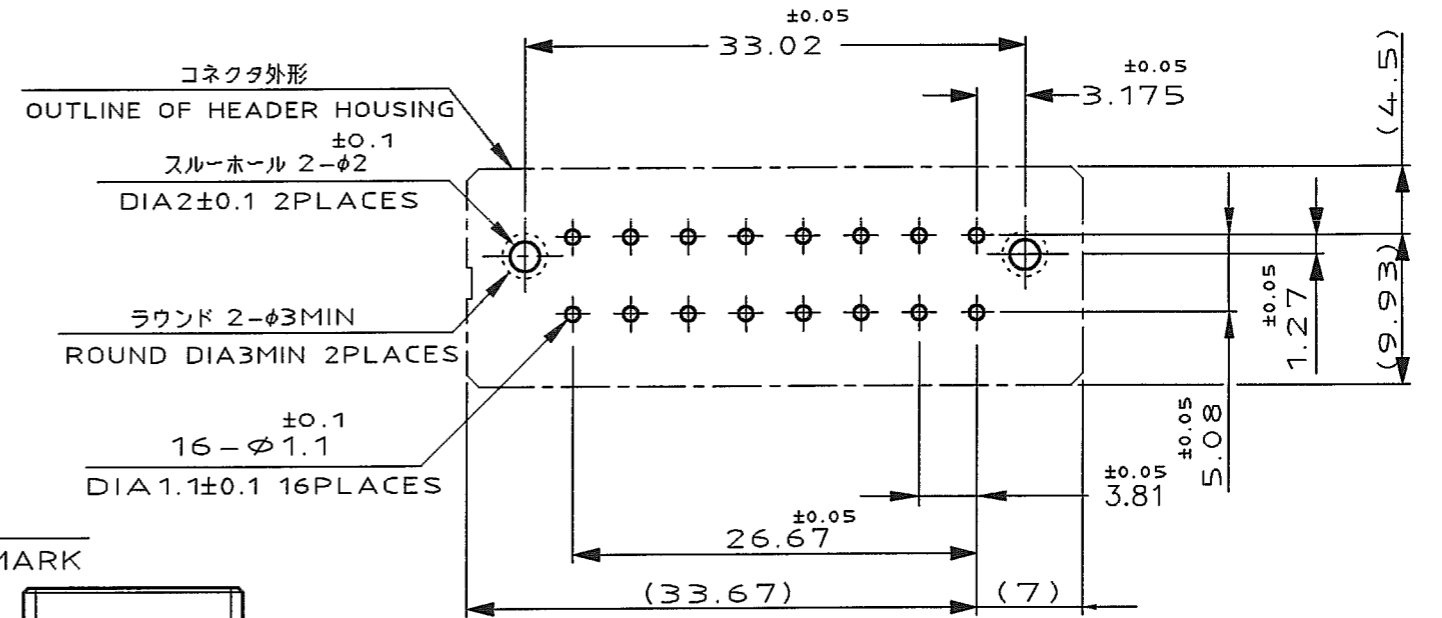
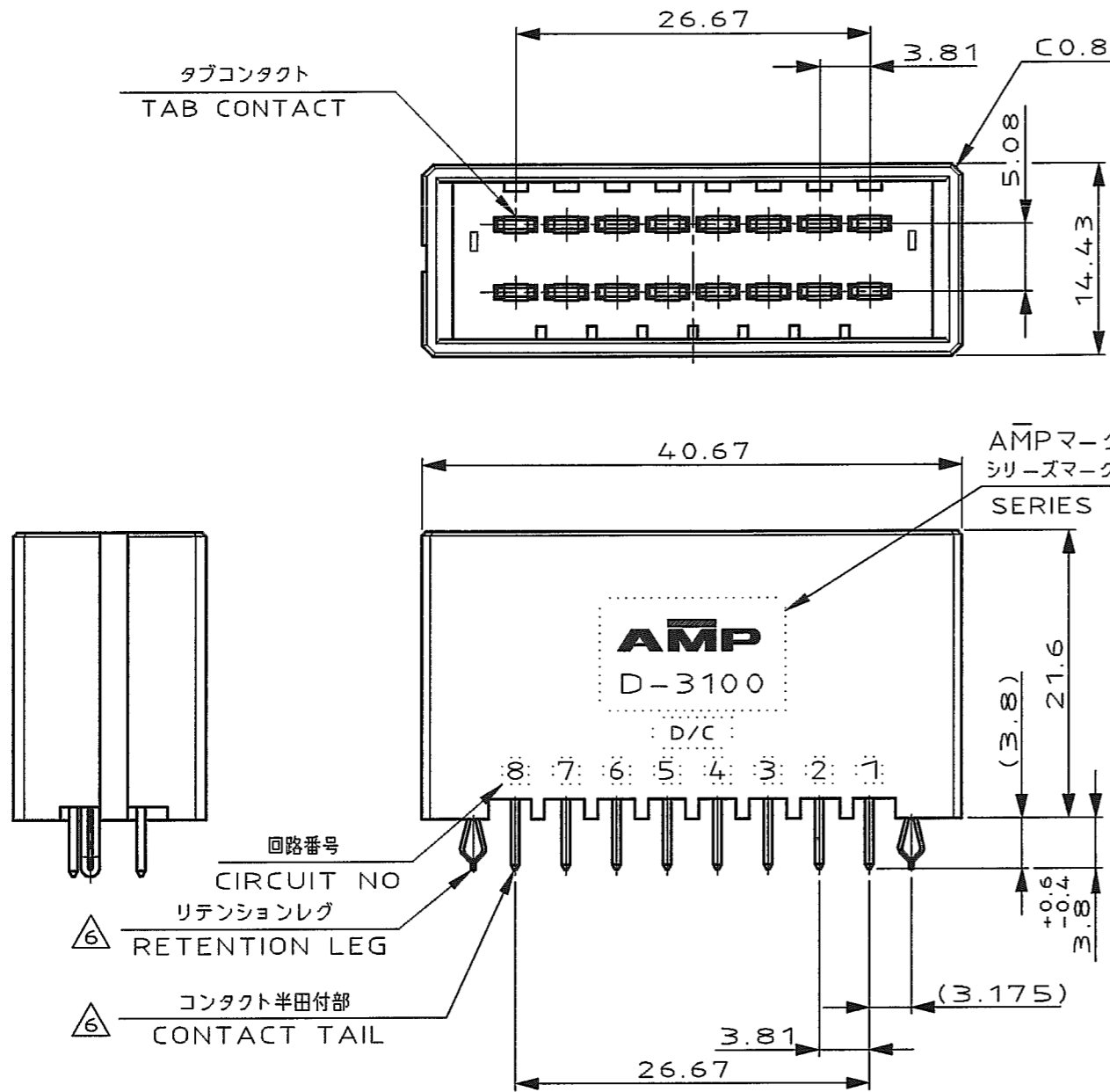
NUMBER 178327



METRIC

DIMENSIONS IN MILLIMETERS. DO NOT SCALE PRINT

PRINT DIST



推奨基板取付け寸法
PC 基板厚:1.6±0.1
(非累積公差)
(コネクタ搭載面)

RECOMEND PC BOARD HOLE PATTERN
PC BOARD THICKNESS:1.6±0.1
(NOT ACCUMULATE TOLERANCE)
(CONNECTOR MOUNT SIDE)

NOTES

- MATERIAL:HOUSING:GLASS FILED THERMO PLASTIC,POLYESTER(94V-0),COLOR:BLACK
CONTACT:CU合金
RETENTION LEG:CU合金
- FINISH(CONTACT AREA):0.38μmMIN GOLD PLATING OVER Ni PLATING
- FINISH(CONTACT AREA):0.76μmMIN GOLD PLATING OVER Ni PLATING
- FINISH(CONTACT AREA):2.0 μmMIN TIN PLATED OVER NICKEL
- FINISH(RETENTION LEG):~~TIN LEAD PLATED~~
(CONTACT TAIL) OVER NICKEL
- FINISH(RETENTION LEG):TIN PLATED
(CONTACT TAIL) OVER NICKEL

注記

- 材料:ハウジング:ガラス入り熱可塑性ポリエステル樹脂(94V-0),色:黒
コンタクト:銅合金
リテンションレグ:銅合金
- めっき:コンタクト:全面Ni下地
接触部:0.38μm MIN金めっき
- めっき:コンタクト:全面Ni下地
接触部:0.76μm MIN金めっき
- めっき:コンタクト:全面Ni下地
接触部:2.0 μm MINスズめっき
- めっき:リテンションレグとコンタクト半田付部
ニッケル下地の上に半田めっき
- めっき:リテンションレグとコンタクト半田付部
ニッケル下地の上にスズめっき

△6	△4	178327-5
△6	△3	178327-3
△6	△2	178327-2
(FINISH)		製品番号 (PART NO.)

REV	DESCRIPTION	DATE	BY	CHK	DATE
E	REVISED	FJDO-0039-03	T.S.S.M.	8/2	
D	REVISED	FJDO-0114-03	T.S.S.M.	25.APR '93	
C	REVISED	FJ00-2744-95	KI.Y.I.	16/JUN '95	
B	REVISED	FJ00-0838-94	NM.S.M.	7/4 '94	
A	REDRAWN WITH CHANGE	FJ00-0480-94	NM.S.M.	4/20 '94	
LTR	REVISION RECORD		DR	CHK	DATE

Copyright © 1994
AMP(Japan) LTD.
ALL RIGHTS RESERVED.



Tyco Electronics AMP K.K
Kawasaki, Japan

WIRE RANGE	INSULATION DIA	NAME	16 POS DOUBLE ROW VERTICAL HDR ASS'Y FOR DYNAMIC D-3100		
mm²(AWG -)	mmφ	一般公差 (GENERAL TOLERANCE)	SIZE	LOC	NUMBER
MATERIAL	FINISH	10MF : ±0.3	A3	J	178327
SEE NOTE 注記参照	SEE NOTE 注記参照	10*30MF : ±0.4	SCALE	REV.	SHEET
DR. 19 APR 94 N.Matsubara	DE. 19 APR 94 N.Matsubara	30*30MF : ±0.45	2-1	E	1 OF 1
CHK. S.MANABE	APP. S.MANABE	角 度 : ±3'			